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October 26, 2007

ASSET® expands next-generation embedded instrumentation

ASSET ScanWorks® provides software solutions for Intel's at-speed design validation and test technology, Interconnect BIST (IBIST)

Richardson, TX – ASSET InterTech is expanding its ScanWorks® system by adding signal integrity analysis applications that support Intel's next-generation embedded instrumentation technology, Intel® IBIST (Interconnect Built In Self Test). ASSET (<http://www.asset-intertech.com/>) is a solutions provider for embedded instrumentation applications such as signal integrity analysis through margining, bit error ratio testing (BERT) and pattern generation testing, as well as boundary-scan (JTAG/IEEE 1149.1) test, in-system programming (ISP) and design-for-test (DFT).

IBIST is anticipated to provide a more effective and much less costly means of validating server platforms which feature high-speed buses, such as PCI Express (PCIe), that are capable of billions of data transfers per second. Intel recently announced that IBIST technology has been embedded into the most recent generations of some of its leading server and workstations platform chipsets, including the 5300 and 7300 Series Quad-Core Intel Xeon® processor-based platforms. ASSET's ScanWorks will also support Intel's next-generation Nehalem processor-based platforms with the Intel QuickPath interconnect.

"Over the last three years, we have evolved ScanWorks to the point where it brings considerable value-added functionality in its role as an easy-to-use design validation, test and debug tool for Intel's embedded instrumentation," said Tim Caffee, ASSET's Vice President for Design Validation, ASSET InterTech. "Embedded instrumentation like Intel's IBIST technology is particularly critical these days because the processing speeds and data transfer speeds of computers and other electronic systems have increased so dramatically. At the high speeds that systems are reaching today, the effectiveness of traditional methods of test and design validation, which rely on physically probing circuit boards, is significantly diminished."

"As the industry's demand for high-speed serial signal architectures continues to grow, we expect to see a growing dependency on IBIST for validating and testing Intel technology," said Lorie Wigle, Intel's Marketing Director of Server Software & Technology Initiatives.

ASSET's ScanWorks environment with support for IBIST consists of software applications for validating and analyzing signal integrity on buses through margining and BERT techniques. ScanWorks interfaces to embedded instruments to validate board-level and system-level designs that feature high-speed buses such as PCI Express, Intel's QuickPath interconnect and others. In addition, ScanWorks features a suite of fault diagnostic tools.

IBIST technology is a design validation and test architecture embedded into many of Intel's processors to enable chip-to-chip interconnect testing and design validation of high-speed buses on a printed circuit board. IBIST leverages the boundary-scan IEEE 1149.1 specification as the hardware and

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software communication methodology for accessing and controlling its embedded on-chip capabilities.

ASSET's boundary scan systems, ScanWorks and DFT Analyzer™, have advanced usability and automation features. ScanWorks has become the boundary-scan test system of choice for practically all major communication and defense/avionics suppliers, including Cisco, Ericsson, Motorola, Lucent, Alcatel, Tellabs, Huawei, Raytheon, Rockwell, Lockheed Martin, BAE, ITT, Northrop Grumman, Smiths and others. In addition, ScanWorks' adoption by companies like Microsoft for its Xbox 360 video game console and Delphi for its automotive electronics demonstrates that ScanWorks will continue its leadership as boundary scan proliferates in computers, set-top boxes, consumer electronics, industrial controls, automotive and other industries.

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ASSET InterTech Inc

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